

AC Electrical Characteristics[†] - Master Mode Output Timing

	Characteristic	Sym.	Min.	Max.	Units	Notes [‡]
1	CKo0 to CKo1 (8.192 MHz) delay	t _{C1D}	-1	2	ns	1-5,16
2	CKo0 to CKo2 (16.384 MHz) delay	t _{C2D}	-1	3	ns	
3	CKo0 to CKo3 (32.768 MHz/16.384 MHz/8.192 MHz/4.096 MHz) delay	t _{C3D}	-4	0	ns	
4	CKo0 to CKo4 delay 2.048 MHz 1.544 MHz	t _{C4D}	-2 -12	3 7	ns	
5	CKo0 to CKo5 (19.44 MHz) delay	t _{C5D}	6	12	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] See "Performance Characteristics Notes" on page 133

AC Electrical Characteristics[†] - Divided Slave Mode Output Timing

	Characteristic	Sym.	Min.	Max.	Units	Notes [‡]
1	CKo0 to CKo1 (8.192 MHz) delay	t _{C1D}	-1	2	ns	1-5,16
2	CKo0 to CKo2 (16.384 MHz) delay	t _{C2D}	-1	3	ns	
3	CKo0 to CKo3 (32.768 MHz/16.384 MHz/8.192 MHz/4.096 MHz) delay	t _{C3D}	-2	2	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] See "Performance Characteristics Notes" on page 133

AC Electrical Characteristics[†] - Multiplied Slave Mode Output Timing

	Characteristic	Sym.	Min.	Max.	Units	Notes [‡]
1	CKo0 to CKo1 (8.192 MHz) delay	t _{C1D}	-1	2	ns	1-5,16
2	CKo0 to CKo2 (16.384 MHz) delay	t _{C2D}	-1	3	ns	
3	CKo0 to CKo3 (32.768 MHz/16.384 MHz/8.192 MHz/4.096 MHz) delay	t _{C3D}	-1	3	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] See "Performance Characteristics Notes" on page 133

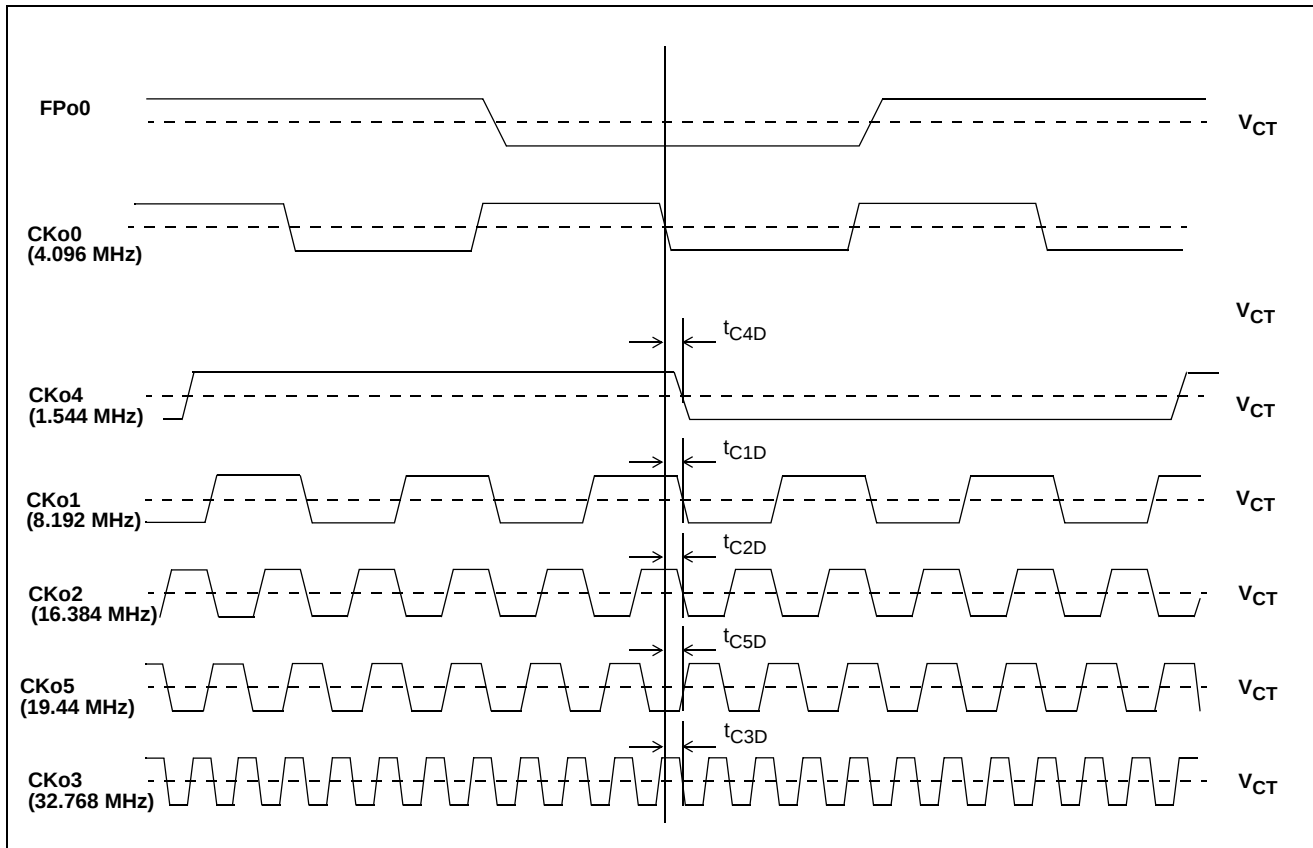


Figure 49 - Output Timing (ST-BUS Format)

DPLL Performance Characteristics[†] - Accuracy & Switching

	Characteristics	Min.	Max.	Units	Conditions/Notes [‡]
1	Freerun Mode accuracy	-0.003	0	ppm	1,5,7
2	Initial Holdover Frequency Stability	-0.03	0.03	ppm	1,4,8
3	Pull-in/Hold-in range (Stratum 3)	-20	20	ppm	1,3,7,9
4	Reference Far Hysteresis Limit (Stratum 3)	-11.4	11.4	ppm	1,3,7,9,15
5	Reference Near Hysteresis Limit (Stratum 3)	-9.8	9.8	ppm	
6	Output phase continuity for reference switch ¹		31	ns	15
7	Normal output phase alignment speed (phase slope)		56	μs/s	10
8	Normal Phase lock time ²		60	s	1,3,7,9,10,12
9	Fast phase lock time		1	s	1,3,7,9,10,11,12

1. Reference switching to normal, holdover, or freerun mode

2. -4.6 to +4.6 ppm locking

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] See "Performance Characteristics Notes" on page 133

DPLL Performance Characteristics[†] - Output Jitter Generation (Unfiltered except for CKo5)

	Characteristics	Typ. [‡]	Units	Conditions/Notes*
1	Jitter at CKo0 and CKo3 (4.096 MHz)	810	ps-pp	1-6,16
2	Jitter at CKo1 and CKo3 (8.192 MHz)	800	ps-pp	
3	Jitter at CKo2 and CKo3 (16.384 MHz)	710	ps-pp	
4	Jitter at CKo3 (4.096, 8.192, 16.384, or 32.768 MHz)	670	ps-pp	
5	Jitter at CKo4 (1.544 MHz or 2.048 MHz)			
	1.544 MHz	1060	ps-pp	
6	2.048 MHz	630	ps-pp	
	Jitter at CKo5 (19.44 MHz)			
	unfiltered jitter	770	ps-pp	
	500 Hz - 1.3 MHz jitter	540	ps-pp	
	65 kHz - 1.3 MHz jitter	460	ps-pp	
	12 kHz - 1.3 MHz jitter	510	ps-pp	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C and are for design aid only: not guaranteed and not subject to production testing.

* See "Performance Characteristics Notes" on page 133.

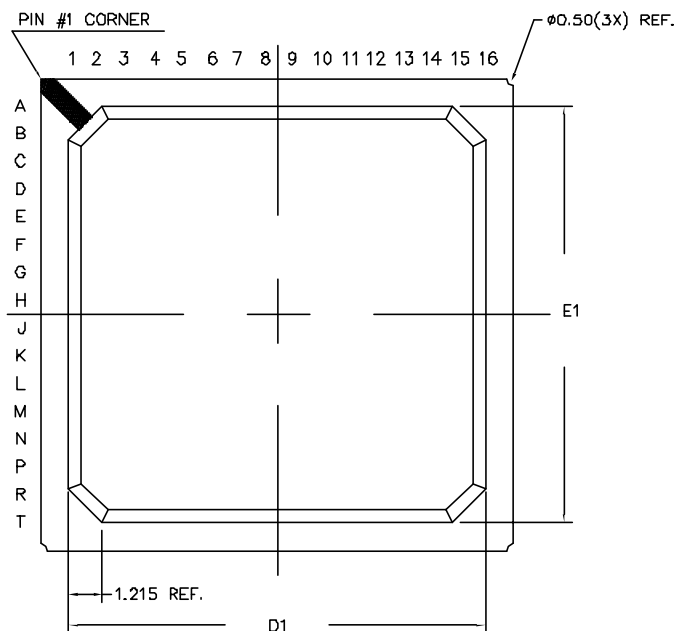
Performance Characteristics Notes

† Characteristics are over recommended operating conditions unless otherwise stated.

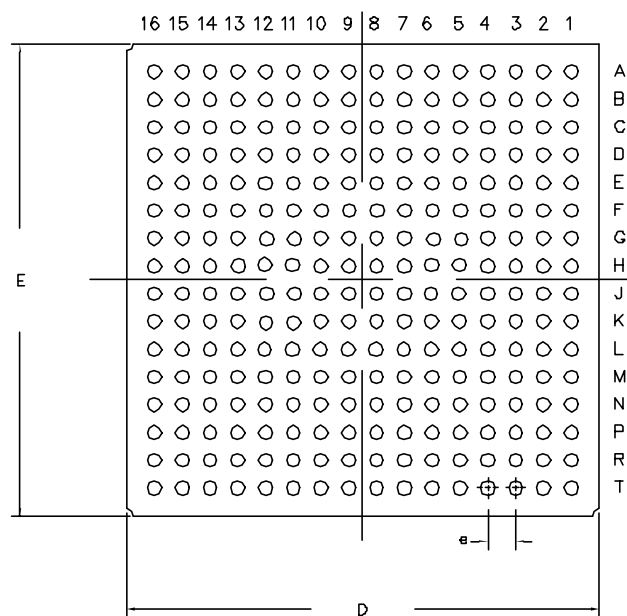
‡ Typical figures are at 25°C, V_{DD_CORE} at 1.8 V and V_{DD_IO} at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

1. Jitter on master clock input (XIN) is 100 ps pp or less.
2. Jitter on reference input (REF0-3) is 2 ns pp or less.
3. Normal Mode selected.
4. Holdover Mode selected.
5. Freerun Mode selected.
6. Jitter is measured without an output filter.
7. Accuracy of master clock input (XIN) is 0 ppm.
8. Accuracy of master clock input (XIN) is 100 ppm.
9. Capture range is programmed to +/-20 ppm; inaccuracy of XIN shifts this range.
10. Phase alignment speed (phase slope) is programmed to 7 ns/125 μ s.
11. Fast lock is enabled.
12. Low pass filter is programmed to 1.9 Hz.
13. Applies to all programmable low pass filter selections of 1.9 Hz and above.
14. Any input reference switch or state switch (e.g.; REF0 to REF3, Normal to Holdover, etc.).
15. Auto-holdover is programmed to 9.913 ppm & 11.287 ppm.
16. 30 pF load on output pin.

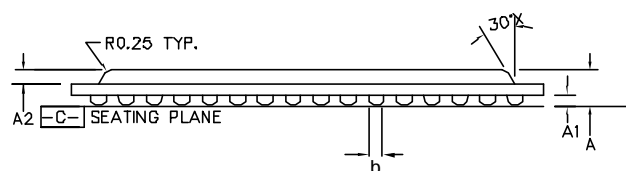
TOP VIEW



BOTTOM VIEW



DIMENSION	MIN	MAX
A	1.42	1.80
A1	0.30	0.50
A2	0.85 REF	
D	16.80	17.20
D1	14.80	15.20
E	16.80	17.20
E1	14.80	15.20
b	0.40	0.60
e	1.00	
N	256	
Conforms to JEDEC MS-034		



SIDE VIEW

NOTES: —

- Controlling dimensions are in MM.
- Seating plane is defined by the spherical crown of the solder balls.
- Not to scale.
- N is the number of solder balls
- Substrate thickness is 0.36 MM.

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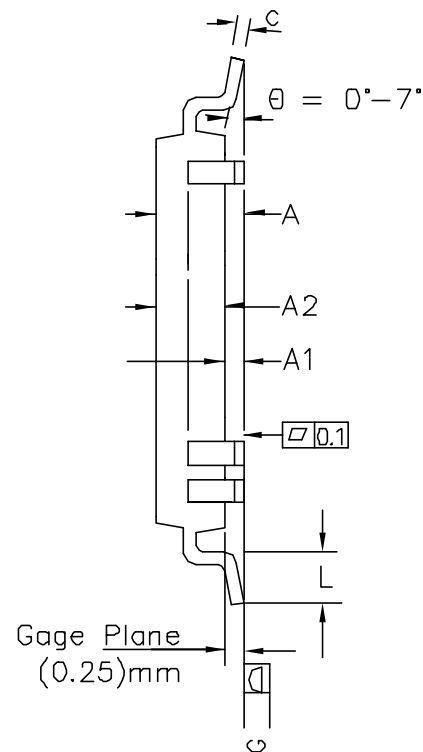
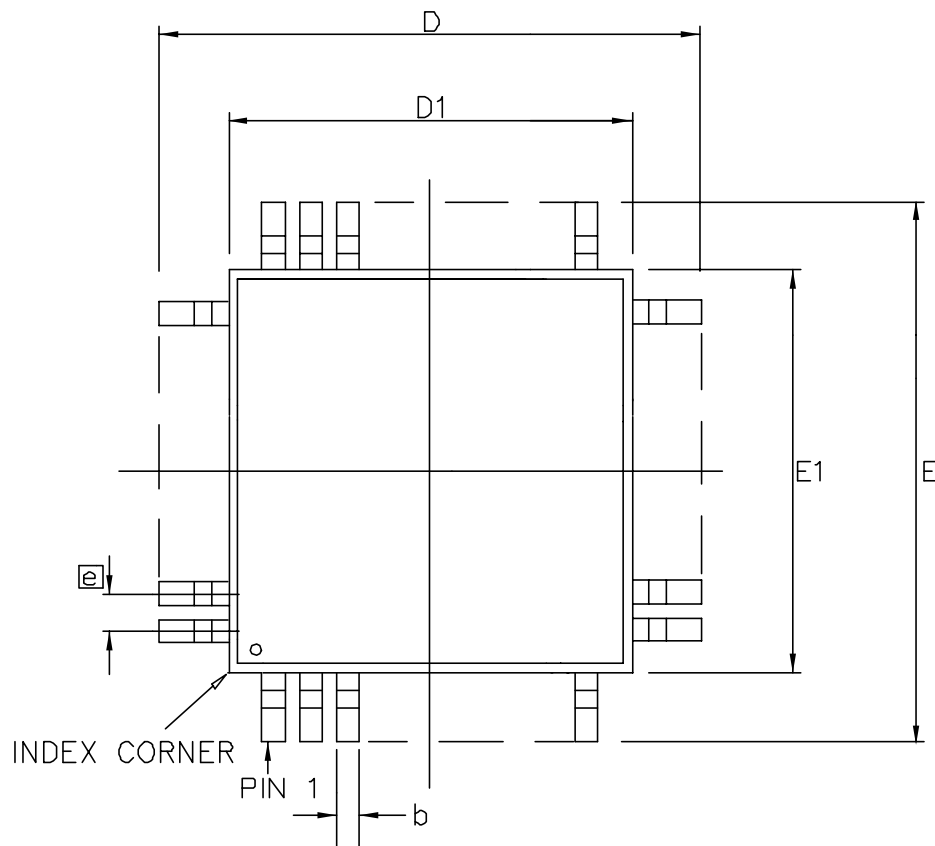
Previous package codes

BP/G

Package Code GA

Package Outline for
256ball BGA
17x17x1.61mm

GPD00842



Symbol	Control Dimensions in millimetres		Altern. Dimensions in inches	
	MIN	MAX	MIN	MAX
A	—	1.60	—	0.063
A1	0.05	0.15	0.002	0.006
A2	1.35	1.45	0.053	0.057
D	30.00 BSC		1.181 BSC	
D1	28.00 BSC		1.102 BSC	
E	30.00 BSC		1.181 BSC	
E1	28.00 BSC		1.102 BSC	
L	0.45	0.75	0.018	0.029
e	0.40 BSC		0.016 BSC	
b	0.13	0.23	0.005	0.009
c	0.09	0.20	0.003	0.008
Pin features				
N	256			
ND	64			
NE	64			
NOTE	SQUARE			

Conforms to JEDEC MS-026 BJC Iss. D

Notes:

1. Pin 1 indicator may be a corner chamfer, dot or both, located within a zone of dimension E1/4 x D1/4 from the index corner
2. All dimensioning and tolerancing conform to ANSI Y14.5-1982.
3. Dimensions D1 and E1 do not include mold protrusion - allowable mold protrusion is 0.254 mm on D1 and E1 dimensions.
4. "N" is the total number of terminals
5. Package top dimensions are smaller than bottom dimensions and top of package will not overhang bottom of package
6. Dimension b does not include Dambar protrusion.
7. Controlling Dimensions are in Millimeter
8. A1 is defined as the distance from the seating plane to the lowest point of the package body

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Previous package codes

GP

Package Code **QC**

Package Outline for 256 lead
LQFP (28 x 28 x 1.4mm)
2.0mm Footprint

GPD00837



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